December 2019 / VOL. 107 / NO. 12

# CONTENTS

## REGULAR PAPERS ISSUE

#### **2308** High-Density Power Conversion and Wide-Bandgap Semiconductor Power Electronics Switching Devices By K. Shenai

**|CONTRIBUTED PAPER|** This article reviews wide-bandgap power semiconductor technologies, which have the potential to transform power conversion electronic systems with increased energy efficiency and reduced cost.

## 2327 Accessing From the Sky: A Tutorial on UAV Communications for 5G and Beyond

By Y. Zeng, Q. Wu, and R. Zhang

|INVITED PAPER| This article provides a tutorial overview of the recent advances in UAV communications, with an emphasis on integrating UAVs into the forthcoming fifth-generation and future cellular networks.

## DEPARTMENTS

#### 2294 POINT OF VIEW

Remotely Sensed Big Data: Evolution in Model Development for Information Extraction By B. Zhang, Z. Chen, D. Peng, J. A. Benediktsson, B. Liu, L. Zou, J. Li, and A. Plaza

### 2302 EDITORIAL

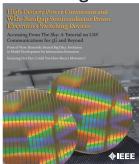
By G. Setti

### **2306** SCANNING THE ISSUE

#### 2376 SCANNING OUR PAST Could You Have Been a Motoneer? By A. B. Magoun

#### 2386 FUTURE SPECIAL ISSUE/SPECIAL SECTIONS

# Proceedings I EEE



# On the Cover:

Our cover image this month highlights wide-bandgap devices by featuring wafers being prepared for production as part of the manufacturing process.